

Features

- Epitaxial Planar Die Construction
- Complementary PNP Types Available (DDTA)
- Built-In Biasing Resistor, R2 Only
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Part Number	R2 (NOM)	Marking
DDTC114GE	10kΩ	N26
DDTC124GE	22kΩ	N27
DDTC144GE	47kΩ	N28
DDTC115GE	100kΩ	N29

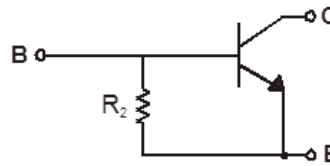
Mechanical Data

- Case: SOT523
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish. Solderable per MIL-STD-202, Method 208⁽³⁾
- Weight: 0.002 grams (Approximate)

SOT523



Top View



Schematic Diagram

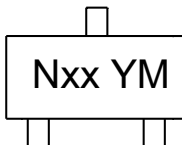
Ordering Information (Note 4)

Part Number	Compliance	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
DDTC114GE-7-F	AEC-Q101	7	8	3,000
DDTC124GE-7-F	AEC-Q101	7	8	3,000
DDTC144GE-7-F	AEC-Q101	7	8	3,000
DDTC115GE-7-F	AEC-Q101	7	8	3,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information

SOT523



Nxx = Product Type Marking Code
(See Table in Features)
YM = Date Code Marking
Y or \bar{Y} = Year (ex: F = 2018)
M or \bar{M} = Month (ex: 9 = September)

Date Code Key

Year	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027
Code	F	G	H	I	J	K	L	M	N	O

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector Base Voltage	V _{CB0}	50	V
Collector-Emitter Voltage	V _{CEO}	50	V
Emitter-Base Voltage	V _{EBO}	5	V
Collector Current	I _C (Max)	100	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation	P _D	150	mW
Thermal Resistance, Junction to Ambient Air (Note 5)	R _{θJA}	833	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CB0}	50	—	—	V	I _C = 50μA
Collector-Emitter Breakdown Voltage	BV _{CEO}	50	—	—	V	I _C = 1mA
Emitter-Base Breakdown Voltage	BV _{EBO}	5	—	—	V	I _E = 720μA, DDTC114GE I _E = 330μA, DDTC124GE I _E = 160μA, DDTC144GE I _E = 72μA, DDTC115GE
Collector Cutoff Current	I _{CBO}	—	—	0.5	μA	V _{CB} = 50V
Emitter Cutoff Current	I _{EBO}	300 140 65 30	—	580 260 130 58	μA	V _{EB} = 4V
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	—	—	0.3	V	I _C = 10mA, I _B = 0.5mA
DC Current Transfer Ratio	h _{FE}	30 56 68 82	—	—	—	I _C = 5mA, V _{CE} = 5V
Bleeder Resistor (R ₂) Tolerance	ΔR ₂	-30	—	+30	%	—
Gain-Bandwidth Product (Note 6)	f _T	—	250	—	MHz	V _{CE} = 10V, I _E = -5mA, f = 100MHz

Notes: 5. Mounted on FR-4 PC Board with minimum recommended pad layout.
6. Transistor only.

Typical Curves – DDTC114GE

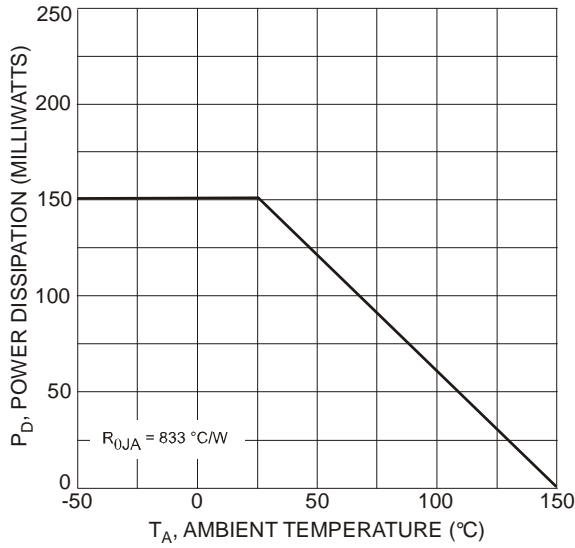


Fig. 1 Derating Curve

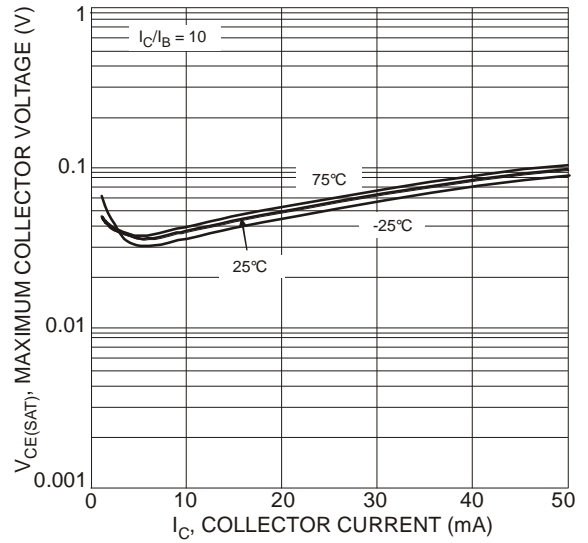


Fig. 2 $V_{CE(SAT)}$ vs. I_C

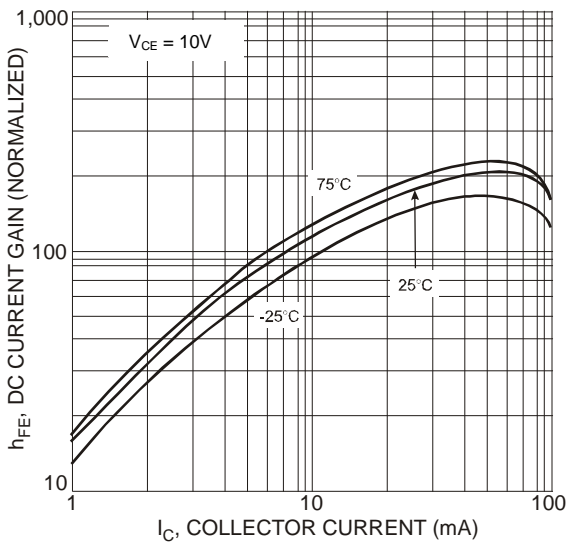


Fig. 3 DC Current Gain

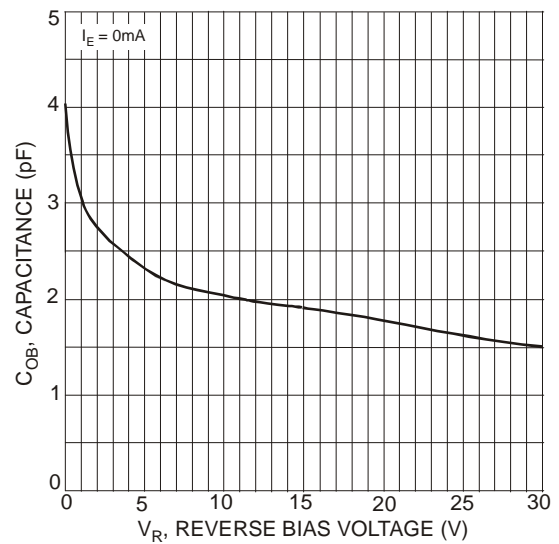


Fig. 4 Output Capacitance

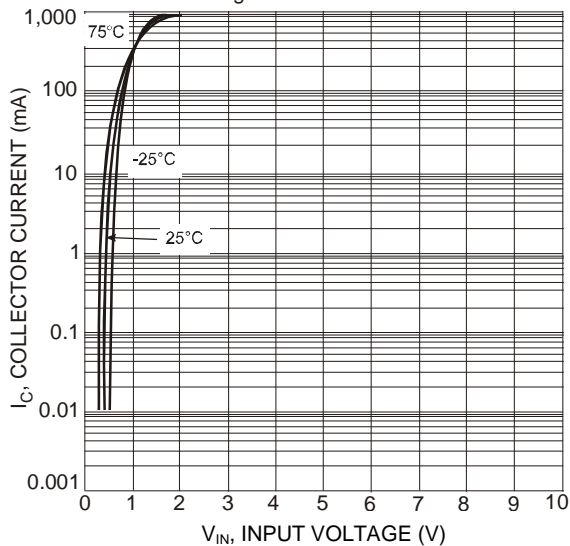


Fig. 5 Collector Current vs. Input Voltage

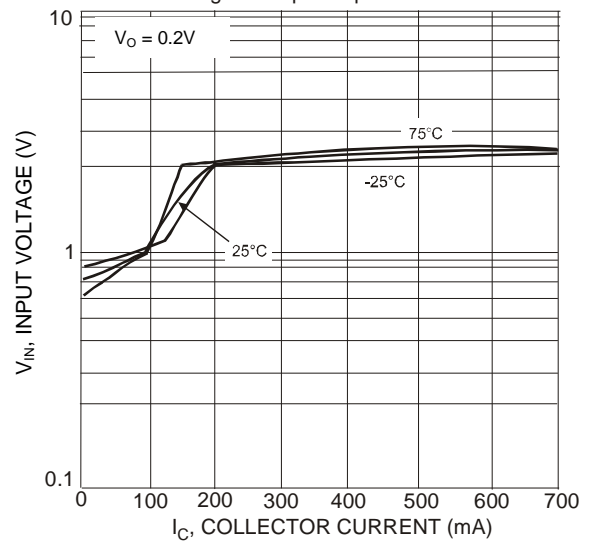
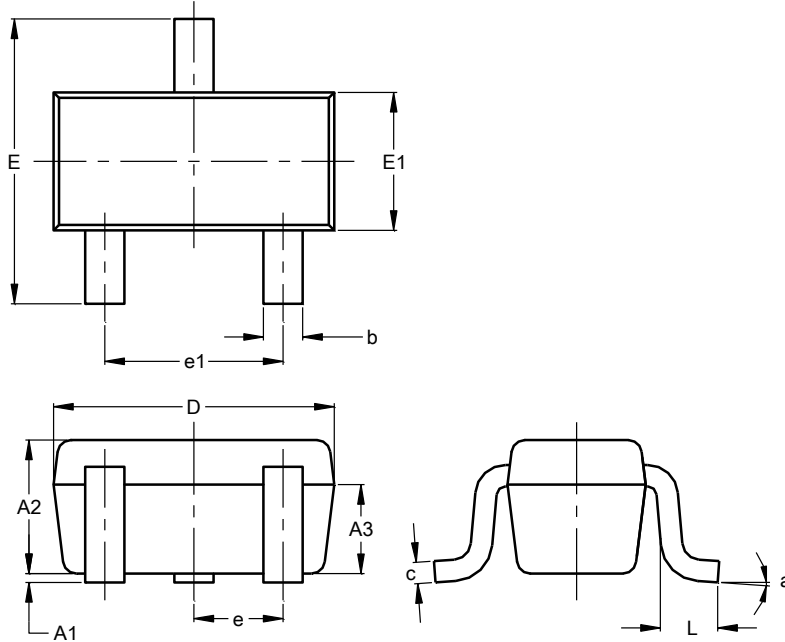


Fig. 6 Input Voltage vs. Collector Current

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

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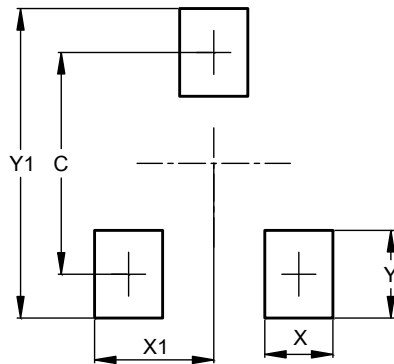


SOT523			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.60	0.80	0.75
A3	0.45	0.65	0.50
b	0.15	0.30	0.22
c	0.10	0.20	0.12
D	1.50	1.70	1.60
E	1.45	1.75	1.60
E1	0.75	0.85	0.80
e	0.50 BSC		
e1	0.90	1.10	1.00
L	0.20	0.40	0.33
a	0°	--	8°
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT523



Dimensions	Value (in mm)
C	1.29
X	0.40
X1	0.70
Y	0.51
Y1	1.80

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